Serial No. 10/814,445

Docket No. 124932-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hong (nmn) Zhong

Serial No.: 10/814,445

Filed: March 30, 2004

For Thermally Conductive Compositions and Methods of

Making Thereof

DEC 1 0 2004 ... EX

Group Art Unit: 1774

Examiner:

INFORMATION DISCLOSURE STATEMENT

X 1	Pursuant to 37CFR 1.97(b) [within 3 months of national, non-CPA filling or prior to 1st Office Action] no charge
□ 2	Certification Pursuant to 37 CFR 1.97(c)(1)
<u> </u>	[before Final Office Action, Allowance, or other action closing prosecution] no charge Fee Payment Pursuant to 37 CFR 1.97(c)(2) [before Final Office Action, Allowance, or other action closing prosecution] \$180.00
4	Certification & Fee Payment Pursuant to 37 CFR 1.97(d) [On or before issue fee payment] \$180.00
COMM	MAILSTOP PATENT APPLICATION ISSIONER FOR PATENTS NDRIA, VA 22313-1450
Sir:	

The following are submitted in the above application in compliance with 37 CFR 1.97 and 37 CFR 1.98:

5 A list of documents on form PTO-1449 or Substitute together with copies of each identified document and a translation thereof or a concise explanation of each non-English language document or a Search Report from an International Searching Authority for a patent application filed via the Patent Cooperation Treaty or document(s) cited in the application or the priority application.

	I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date indicated below.
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This paper is submitted in accordance with:

[X] 6 37 CFR 1.97(b): [within 3 months of national, non-CPA filing or prior to 1st Office Action]

[X] 7 37 CFR 1.97(c): [before Final Office Action, Allowance, or other action closing prosecution, whichever is earlier]; and

[X] 8 The required Certification made in item 11 below;

[X] 9 The \$180.00 fee specified in 37 CFR 1.17(p) for submission of this Information Disclosure Statement is authorized in item 15 below.

[X] 10 37 CFR 1.97(d): [on or before issue fee payment]; and

b) The \$100,00 fee exceitied in 27 CED 1.17(a) fee

b) The \$180.00 fee specified in 37 CFR 1.17(p) for submission of this Information Disclosure Statement is authorized in item 14 below.

The required Certification is stated in item 11 below; and

☐ 11 Certification

a)

Each item of information contained in this Statement was first cited in any communication from a foreign patent office in a counterpart foreign patent application not more than three months prior to the filing of this Statement; or

No item contained in this Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the person signing this document after making reasonable inquiry, no item of information contained in this Statement was known to any individual designated in 37 CFR 1.56(c) more than three (3) months prior to the filing date of this Statement.

Please charge all applicable fees associated with the submittal of this Information Disclosure Statement to Deposit Account No. 07-0868

An original and two (2) copies of this document are enclosed.

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General Electric Company GEGR Patent Docket Rm. Bldg. K-1 Rm. 4A59 One Research Circle

Niskayuna, New York 12309 Customer Number: 006147 Respectfully submitted,

Attorney - Patrick K. Patnode Registration No. 40,121

Phone: (518) 387-5286 or (518) 387-7122

US Patent Application Publication 2003/0027910A1, entitled "Morphing Fillers and Thermal Interface Materials", Sanjay Misra et al., published 2/6/03 US Patent Application Publication 2003/0077478A1, entitled "Thermal Interface Material and Electronic Assembly Having Such a Thermal Interface Material, Ashay A. Dani et al.,, published 4/24/03 "Hybrid Organic Inorganic Materials - in Search of Synergic Activity" by Pedro Gomez-Romero, Advanced Materials, 2001, Vol. 13, No.3, pp. 163-174

EXAMINER

DATE CONSIDERED

(REV 7-80) PATENT AND TRADEMARK OF (Title Amended 3/83)												, mill booker no.			10/814,445		
INFÓRMATION DISCLOSURE STATEMENT BY APPLICANT											Т	Applicant Hong (nmn) Zhong					
<u>LIST OF ITEMS</u>												Filing Date		Group	Group		
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	"Inorganic Clusters in Organic Polymers and the Use of Polyfunctional Inorganic Compounds as Polymerization Initiators" by Guido Kickelbick and Ulrich Schubert, Monatshefte fur Chemie,																
	2001, Vol. 132, pp. 13-30 "Synthesis and Application of Inorganic/Organic Composite Materials", by Helmut Schmidt, Macromolecular Symposia, 1996, Vol. 101, pp. 333-342																
	"Synthesis of Nanocomposite Organic/Inorganic Hybrid Materials Using Controlled/ 'Living' Radical Polymerization" by Jeffrey Pyun and Krzysztof Matyjaszewski, Chemistry of Materials, 2001, Vol. 13, pp.3436-3448																
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.